



## Material Content Data Sheet



<b>Sales Product Name</b>		BFP 840FESD H6327		<b>Issued</b>		29. August 2013		
<b>MA#</b>		MA000993432						
<b>Package</b>		PG-TSFP-4-1		<b>Weight*</b>		1.96 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.020	1.03	1.03	10308	10308
leadframe	inorganic material	silicon	7440-21-3	0.000	0.01		76	
	non noble metal	titanium	7440-32-6	0.001	0.04		377	
	non noble metal	chromium	7440-47-3	0.002	0.11		1129	
wire	non noble metal	copper	7440-50-8	0.734	37.48	37.64	374781	376363
	noble metal	gold	7440-57-5	0.008	0.39	0.39	3853	3853
	encapsulation	organic material	carbon black	1333-86-4	0.010	0.49		4858
encapsulation	plastics	epoxy resin	-	0.205	10.44		104445	
	inorganic material	silicondioxide	60676-86-0	0.738	37.64	48.57	376488	485791
leadfinish	non noble metal	tin	7440-31-5	0.049	2.50	2.50	24983	24983
plating	noble metal	silver	7440-22-4	0.090	4.60	4.60	45954	45954
solder	non noble metal	tin	7440-31-5	0.021	1.08		10813	
	noble metal	gold	7440-57-5	0.082	4.19	5.27	41935	52748
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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